

AMENDMENTS TO THE CLAIMS:

10/7/26/23 ✓

The listing of claims shown below will replace all prior versions, and listings, of claims in the Application:

✓ ④ (Currently Amended) A method of forming  $\text{MgB}_2$  films *in-situ* on a substrate comprising the steps:

- (a) depositing boron onto a surface of the substrate in a depressurized deposition zone; ✓
- (b) moving the substrate into a reaction zone containing pressurized gaseous magnesium, the reaction zone being substantially sealed from the depressurized deposition zone; ~~112 - I, 11~~
- (c) moving the substrate back into the deposition zone; and
- (d) repeating steps (a)-(c).

✓ ② (Original) The method of claim 1, wherein the movement of steps (b) and (c) is produced by rotating the substrate on a platen.

✓ ③ (Original) The method of claim 2, wherein the platen is rotated at a rate within the range of about 100 rpm to about 500 rpm.

✓ ④ (Original) The method of claim 1, wherein the substrate is heated to a temperature within the range of about 300°C to about 700°C.

Y 5 (Original) The method according to claim 1, wherein the substrate is selected from the group consisting of LSAT,  $\text{LaAlO}_3$ ,  $\text{MgO}$ ,  $\text{SrTiO}_3$ , r-plane sapphire, c-plane sapphire, m-plane sapphire, yttria-stabilized zirconia (YSZ), silicon carbide, polycrystalline alumina, silicon, and stainless steel.

Y 8 (Currently Amended) The method of claim 1, wherein the reaction zone contains gaseous magnesium at a partial pressure of about 10 mTorr. A  $\text{MgB}_2$  film produced by the method of claim 1.

Y 9 (Original) The method according to claim 1, wherein the reaction zone is coupled to a heated source of magnesium.

Y 10 (Original) The method according to claim 1, wherein the substrate is a wafer.

Y 11 (Original) The method according to claim 1, wherein the substrate is a tape.

Y 12 (Original) The method according to claim 1, wherein the method is used to form  $\text{MgB}_2$  on a plurality of substrates.

Y 13 (Currently Amended) The method of claim 1, wherein the boron is evaporated ~~the film of  $\text{MgB}_2$  is generated under~~ at a pressure of less than  $10^{-6}$  Torr in the

deposition zone.

12. (Original) The method of claim 1, wherein the  $MgB_2$  film is formed on a single side of the substrate.

13. (Currently Amended) A method of forming  $MgB_2$  films *in-situ* on a substrate comprising the steps:

- (a) depositing boron onto a surface of the substrate in a deposition zone;
- (b) moving the substrate into a reaction zone containing pressurized gaseous magnesium;
- (c) moving the substrate back into the deposition zone; and
- (d) repeating steps (a)-(c);

~~The method of claim 1, wherein the  $MgB_2$  film is formed on two sides of the substrate.~~

14. (Currently Amended) A method of forming a film of  $MgB_2$  *in-situ* comprising the steps of:

providing a rotatable platen, the platen being rotatable within a housing having a pressurized reaction zone and a separate depressurized deposition zone, the pressurized reaction zone being substantially sealed from the depressurized deposition zone;

providing an evaporation cell operatively coupled to the pressurized reaction zone, the evaporation cell containing magnesium;

providing a source of boron disposed adjacent to the depressurized deposition zone;

providing an electron beam gun aimed at the source of boron;

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loading a substrate onto the platen;  
rotating the platen;  
heating the local environment around the substrate;  
heating the evaporation cell so as to produce pressurized gaseous magnesium in  
the reaction zone; and  
evaporating the boron with the electron beam gun.

Y 15. (Original) The method according to claim 14, wherein the local  
environment around the substrate is heated to a temperature within the range of about  
300°C to about 700°C.

Y 16. (Original) The method according to claim 14, wherein the evaporation cell  
is heated to a temperature of at least 550°C.

Y 17. (Original) The method according to claim 14, wherein the platen is rotated  
at a rate within the range of about 100 rpm to about 500 rpm.

Y 18. (Original) The method according to claim 14, wherein the substrate is  
selected from the group consisting of LSAT, LaAlO<sub>3</sub>, MgO, SrTiO<sub>3</sub>, r-plane sapphire, c-  
plane sapphire, m-plane sapphire, yttria-stabilized zirconia (YSZ), silicon carbide,  
polycrystalline alumina, silicon, and stainless steel.

Y 19. (Original) The method of claim 14, wherein the substrate is a wafer.

20. (Original) The method of claim 14, wherein the substrate is a tape.
21. (Original) The method of claim 14, wherein the step of loading the platen comprises loading the platen with a plurality of substrates.
22. (Currently Amended) The method of claim 14, wherein the boron is evaporated ~~the film of MgB<sub>2</sub> is generated under~~ at a pressure of less than 10<sup>-6</sup> Torr in the deposition zone.
23. (Original) The method of claim 14, wherein a film of MgB<sub>2</sub> is formed on a single side of the substrate.
24. (Currently Amended) A method of forming a film of MgB<sub>2</sub> *in-situ* comprising the steps of:
- providing a rotatable platen, the platen being rotatable within a housing having a reaction zone and a separate deposition zone;
  - providing an evaporation cell operatively coupled to the reaction zone, the evaporation cell containing magnesium;
  - providing a source of boron disposed adjacent to the deposition zone;
  - providing an electron beam gun aimed at the source of boron;
  - loading a substrate onto the platen;
  - rotating the platen;

heating the local environment around the substrate;

heating the evaporation cell so as to produce gaseous magnesium in the reaction zone; and

evaporating the boron with the electron beam gun;

The method of claim 14, further comprising the steps of removing the substrate from the platen;

turning the substrate over;

loading the substrate onto the platen;

rotating the platen;

heating the local environment around the substrate;

heating the evaporation cell so as to produce pressurized gaseous magnesium in the reaction zone; and

evaporating the boron with the electron beam gun.

25. (Currently Amended) The method of claim 14, wherein the reaction zone contains gaseous magnesium at a partial pressure of about 10 mTorr. A MgB<sub>2</sub> film produced by the method of claim 14.

26. (Currently Amended) A method of forming a superconducting film of a known superconducting compound *in-situ* on a substrate comprising the steps:

(a) depositing one or more elements of the superconductor onto a surface of the substrate in a depressurized deposition zone having a pressure less than about 10<sup>-5</sup> Torr;

(b) heating a non-gaseous element of the superconductor so as to produce a

pressurized gaseous phase of the element inside a (reaction zone), the reaction zone being substantially sealed from the depressurized deposition zone and being substantially free of oxygen; ~~112-11, 11~~

(c) moving the substrate into the reaction zone containing the pressurized gaseous element;

(d) moving the substrate back into the depressurized deposition zone; and

(e) repeating steps (a)-(d).

~~27~~ (Currently Amended) The method of claim 26, wherein the superconducting film is a ~~superconductor selected from the group consisting of~~ magnesium diboride, YBCO, BSCCO, TBCCO, and HBCCO.

~~28~~ (Currently Amended) A method of forming a film of a known compound in-situ on a substrate comprising the steps:

(a) depositing one or more elements of the compound onto a surface of the substrate in a one of a plurality of depressurized deposition zones;

(b) heating a non-gaseous element of the compound so as to produce a pressurized gaseous phase of the element inside a plurality of reaction zones, each reaction zone being substantially sealed from the depressurized deposition zones; ~~112-11, 11~~

(c) moving the substrate into a next the reaction zone containing the pressurized gaseous element;

(d) moving the substrate back into the a next depressurized deposition zone; and

(e) repeating steps (a)-(d).

X ~~28~~ (Original) The method of claim 28, wherein the compound is a superconductor.

X ~~30~~ (New) The method of claim 26, wherein step (c) further comprises moving the substrate into another reaction zone containing oxygen.

X ~~31~~ (New) The method of claim 30, wherein the superconducting film is a superconductor selected from the group consisting of YBCO, BSCCO, TBCCO, and HBCCO.